



512Kx16 SRAM MODULE

FEATURES

- Access Times 17, 20, 25, 35ns
- MIL-STD-883 Compliant Devices Available
- Packaging
 - 44 pin Ceramic SOJ (Package 102)
 - 44 lead Ceramic Flatpack (Package 209)
- Organized as two banks of 256Kx16
- Data Byte Control:
 - Lower Byte (LB#) = I/O1-8
 - Upper Byte (UB#) = I/O9-16
- Data I/O Compatible with 3.3V devices
- 2V Minimum Data Retention for battery back up operation
- Commercial, Industrial and Military Temperature Range
- 5 Volt Power Supply (3.3V parts also available)
- Low Power CMOS
- TTL Compatible Inputs and Outputs

* This product is under development, is not qualified or characterized and is subject to change or cancellation without notice.

PIN CONFIGURATION FOR WS512K16-XXX

**44 CSOJ
44 FLATPACK**

Top View

A0 □ 1 44 □ A17
 A1 □ 2 43 □ A16
 A2 □ 3 42 □ A15
 A3 □ 4 41 □ OE#
 A4 □ 5 40 □ UB#
 CS1# □ 6 39 □ LB#
 I/O1 □ 7 38 □ I/O16
 I/O2 □ 8 37 □ I/O15
 I/O3 □ 9 36 □ I/O14
 I/O4 □ 10 35 □ I/O13
 Vcc □ 11 34 □ GND
 GND □ 12 33 □ Vcc
 I/O5 □ 13 32 □ I/O12
 I/O6 □ 14 31 □ I/O11
 I/O7 □ 15 30 □ I/O10
 I/O8 □ 16 29 □ I/O9
 WE# □ 17 28 □ CS2#
 A5 □ 18 27 □ A14
 A6 □ 19 26 □ A13
 A7 □ 20 25 □ A12
 A8 □ 21 24 □ A11
 A9 □ 22 23 □ A10

Pin Description

A0-17	Address Inputs
LB#	Lower-Byte Control (I/O1-8)
UB#	Upper-Byte Control (I/O9-16)
I/O1-16	Data Input/Output
CS1-2#	Chip Select
OE#	Output Enable
WE#	Write Enable
Vcc	+5.0V Power
GND	Ground
NC	No Connection

Block Diagram

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TRUTH TABLE

CS1#	CS2#	WE#	OE#	LB#	UB#	Mode	Data I/O		Power
H	H	X	X	X	X	Not Select	I/O1-8	I/O9-16	Standby
L	H	H	H	X	X	Output Disable	High Z	High Z	Active
H	L								
L	H	X	X	H	H				
H	L								
H	L	H	L	L	H	Read	Data Out	High Z	Active
L	H			H	L		High Z	Data Out	
L	L			L	L		Data Out	Data Out	
H	L	L	H	L	H	Write	Data In	High Z	Active
L	H			H	L		High Z	Data In	
L	L			L	L		Data In	Data In	

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit
Operating Temperature	T _A	-55	+125	°C
Storage Temperature	T _{STG}	-65	+150	°C
Signal Voltage Relative to GND	V _G	-0.5	V _{CC} +0.5	V
Junction Temperature	T _J		150	°C
Supply Voltage	V _{CC}	-0.5	7.0	V

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Max	Unit
Supply Voltage	V _{CC}	4.5	5.5	V
Input High Voltage	V _{IH}	2.2	V _{CC} + 0.3	V
Input Low Voltage	V _{IL}	-0.3	+0.8	V
Operating Temp. (MIL)	T _A	-55	+125	°C

CAPACITANCE

T_A = +25°C

Parameter	Symbol	Conditions	Max	Unit
Input capacitance	C _{IN}	V _{IN} = 0V, f = 1.0 MHz	25	pF
Output capacitance	C _{OUT}	V _{OUT} = 0V, f = 1.0 MHz	25	pF

This parameter is guaranteed by design but not tested.

DC CHARACTERISTICS

V_{CC} = 5.0V, V_{SS} = 0V, -55°C ≤ T_A ≤ +125°C

Parameter	Sym	Conditions	Min	Max	Units
Input Leakage Current	I _{LI}	V _{CC} = 5.5, V _{IN} = GND to V _{CC}		10	µA
Output Leakage Current	I _{LO}	CS# = V _{IH} , OE# = V _{IH} , V _{OUT} = GND to V _{CC}		10	µA
Operating Supply Current	I _{CC}	CS# = V _{IL} , OE# = V _{IH} , f = 5MHz, V _{CC} = 5.5		290	mA
Standby Current	I _{SB}	CS# = V _{IH} , OE# = V _{IH} , f = 5MHz, V _{CC} = 5.5		30	mA
Output Low Voltage	V _{OL}	I _{OL} = 8mA, V _{CC} = 4.5		0.4	V
Output High Voltage	V _{OH}	I _{OH} = -4.0mA, V _{CC} = 4.5	2.4		V

NOTE: DC test conditions: V_{IH} = V_{CC} - 0.3V, V_{IL} = 0.3V

DATA RETENTION CHARACTERISTICS

-55°C ≤ T_A ≤ +125°C

Characteristic	Sym	Conditions	Min	Typ	Max	Units
Data Retention Supply Voltage	V _{DR}	CS# ≥ V _{CC} - 0.2V	2.0		5.5	µA
Data Retention Current	I _{CCDR1}	V _{CC} = 3V		2.0	12.0*	mA

* Also available in Low Power version. Please call factory for information.



AC CHARACTERISTICS

V_{CC} = 5.0V, GND = 0V, -55°C ≤ T_A ≤ +125°C

Parameter Read Cycle	Symbol	-17		-20		-25		-35		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
Read Cycle Time	t _{RC}	17		20		25		35		ns
Address Access Time	t _{AA}		17		20		25		35	ns
Output Hold from Address Change	t _{OH}	0		0		0		0		ns
Chip Select Access Time	t _{ACS}		17		20		25		35	ns
Output Enable to Output Valid	t _{OE}		10		12		15		20	ns
Chip Select to Output in Low Z	t _{CLZ} ¹	2		5		5		5		ns
Output Enable to Output in Low Z	t _{OLZ} ¹	0		0		0		0		ns
Chip Disable to Output in High Z	t _{CHZ} ¹		9		10		12		15	ns
Output Disable to Output in High Z	t _{OHZ} ¹		9		10		12		15	ns
LB#, UB# Access Time	t _{BA}		10		12		14		17	ns
LB#, UB# Enable to Low Z Output	t _{BLZ1}	0		0		0		0		ns
LB#, UB# Disable to High Z Output	t _{BHZ1}		9		10		12		15	ns

1. This parameter is guaranteed by design but not tested.

AC CHARACTERISTICS

V_{CC} = 5.0V, GND = 0V, -55°C ≤ T_A ≤ +125°C

Parameter Write Cycle	Symbol	-17		-20		-25		-35		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
Write Cycle Time	t _{WC}	17		20		25		35		ns
Chip Select to End of Write	t _{CW}	14		17		20		25		ns
Address Valid to End of Write	t _{AW}	14		17		20		25		ns
Data Valid to End of Write	t _{DW}	10		12		15		20		ns
Write Pulse Width	t _{WP}	14		17		20		25		ns
Address Setup Time	t _{AS}	0		0		0		0		ns
Address Hold Time	t _{AH}	0		0		0		0		ns
Output Active from End of Write	t _{OW} ¹	0		0		0		0		ns
Write Enable to Output in High Z	t _{WHZ} ¹		9		10		10		15	ns
Data Hold Time	t _{DH}	0		0		0		0		ns
LB#, UB# Valid to End of Write	t _{BW}	14		17		20		25		ns

1. This parameter is guaranteed by design but not tested.

AC TEST CIRCUIT

The diagram shows an AC test circuit. It features a bridge circuit with four diodes. A D.U.T. (Device Under Test) is connected to the bridge. A current source is connected to the top node, and another current source is connected to the bottom node. The output current is labeled I_{OL} and I_{OH}. A bipolar supply V_Z = 1.5V is connected to the bridge. A capacitor C_{eff} = 50 pf is connected to the D.U.T. input.

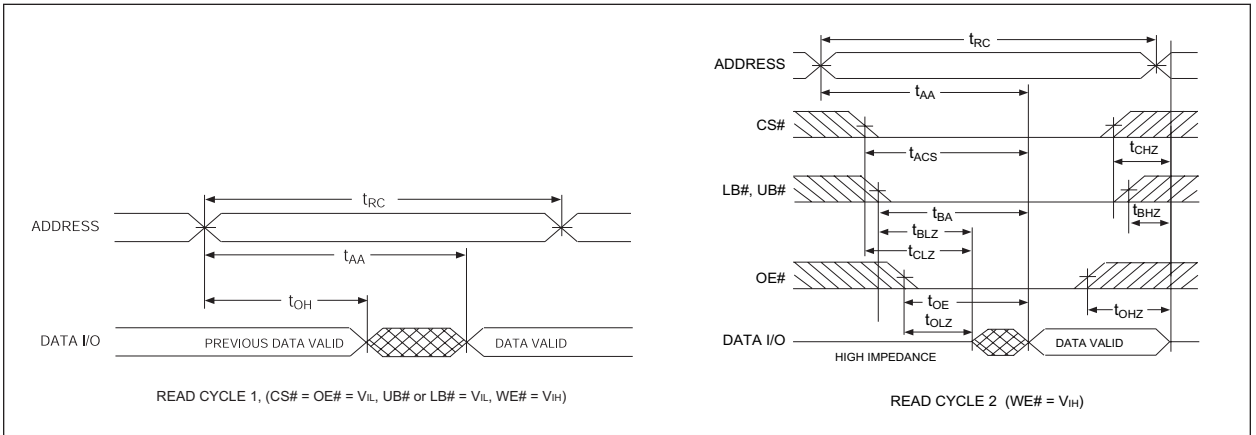
AC Test Conditions

Parameter	Typ	Unit
Input Pulse Levels	V _{IL} = 0, V _{IH} = 3.0	V
Input Rise and Fall	5	ns
Input and Output Reference Level	1.5	V
Output Timing Reference Level	1.5	V

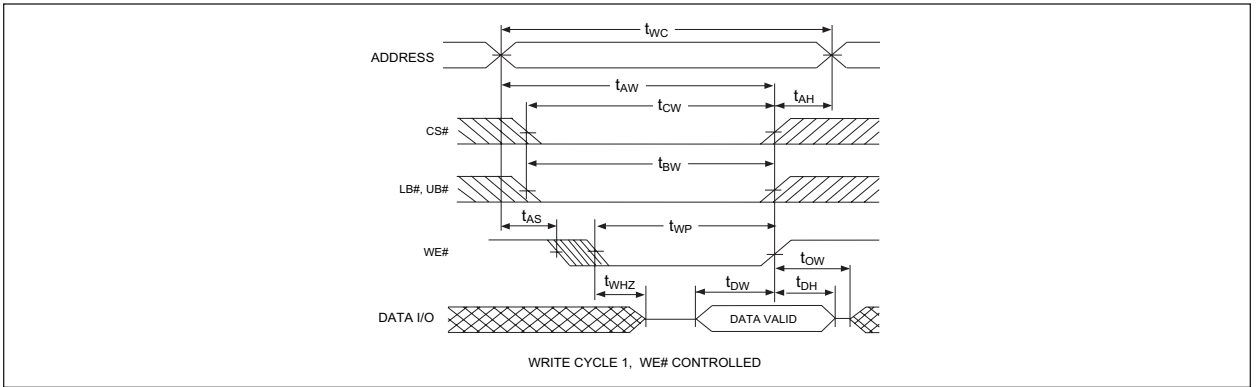
Notes:
V_Z is programmable from -2V to +7V.
I_{OL} & I_{OH} programmable from 0 to 16mA.
Tester Impedance Z₀ = 75Ω.
V_Z is typically the midpoint of V_{OH} and V_{OL}.
I_{OL} & I_{OH} are adjusted to simulate a typical resistive load circuit.
ATE tester includes jig capacitance.



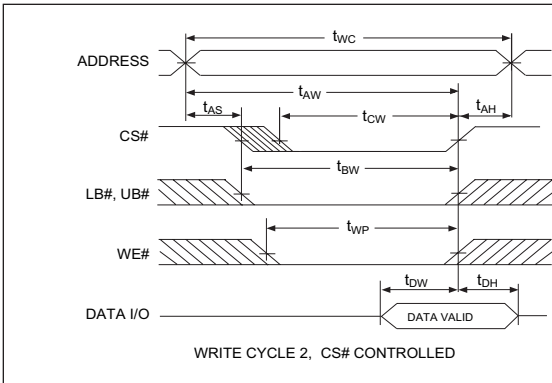
TIMING WAVEFORM – READ CYCLE



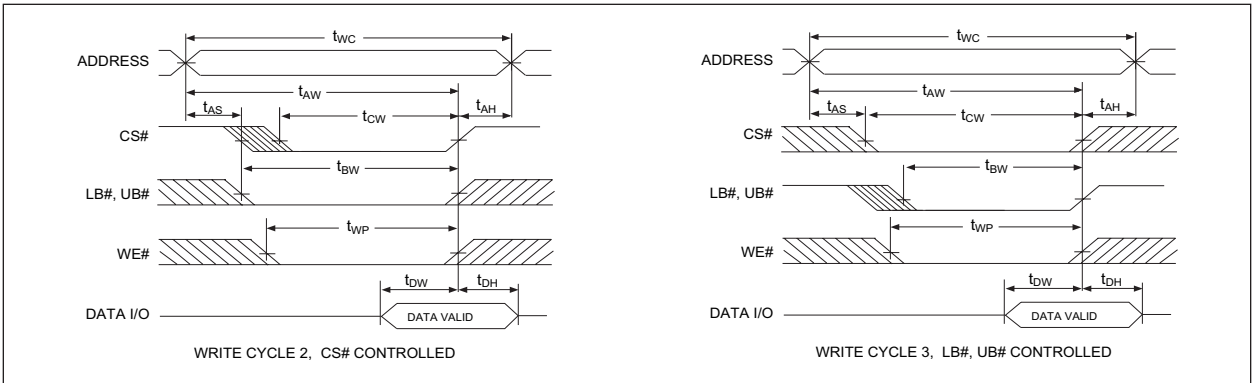
WRITE CYCLE – WE# CONTROLLED



WRITE CYCLE – CS# CONTROLLED

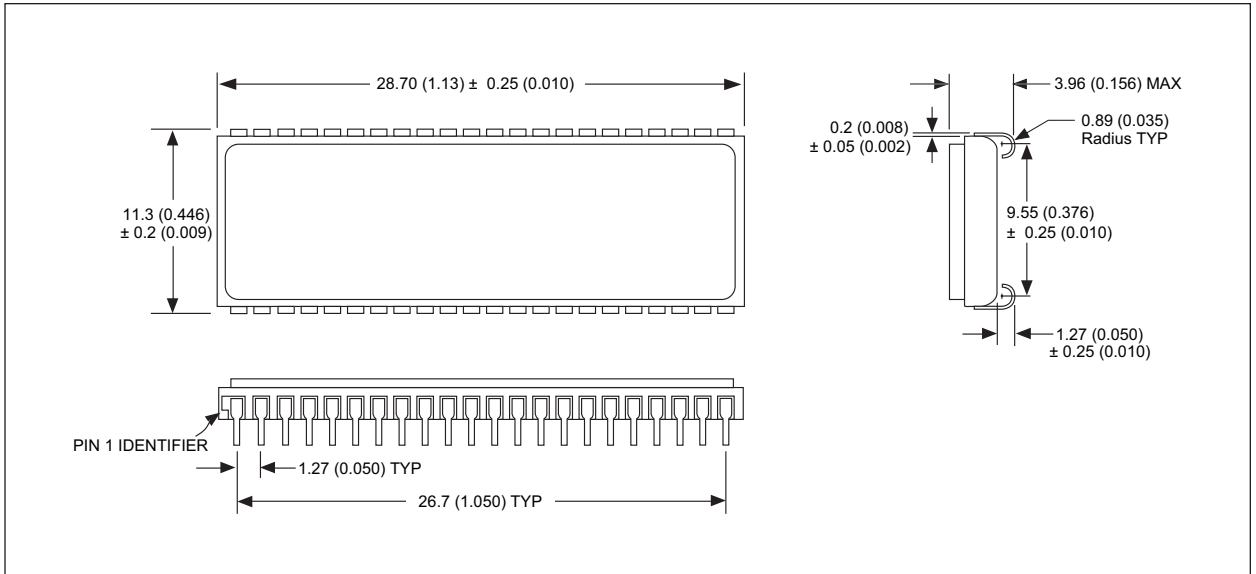


WRITE CYCLE – LB#, UB# CONTROLLED



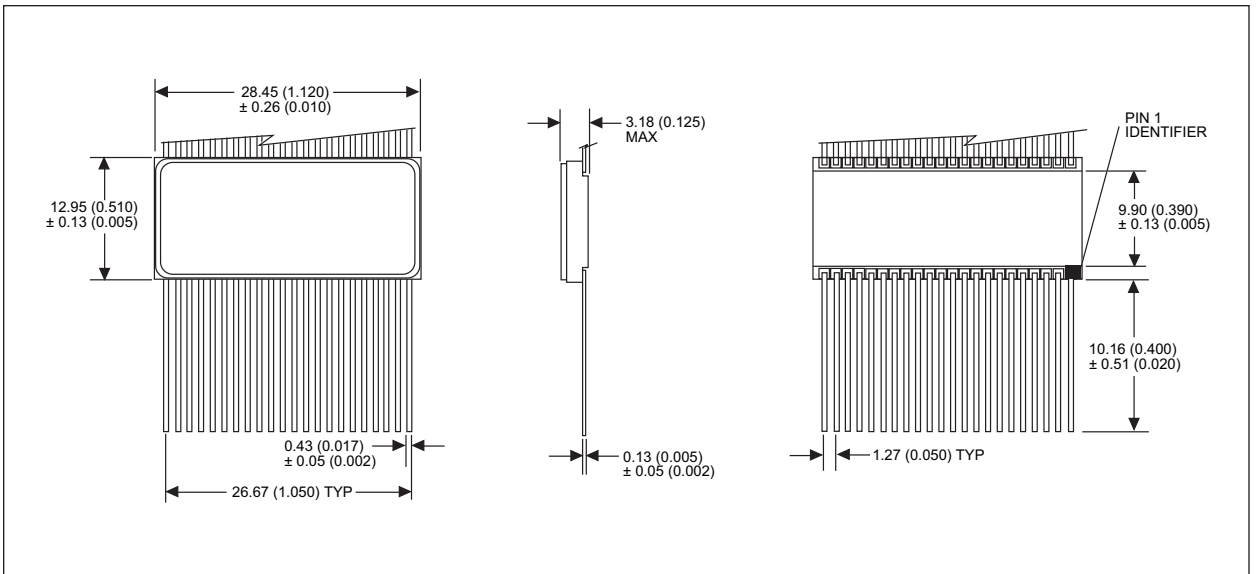


PACKAGE 102: 44 LEAD, CERAMIC SOJ



ALL LINEAR DIMENSIONS ARE MILLIMETERS AND PARENTHETICALLY IN INCHES

PACKAGE 209: 44 LEAD, CERAMIC FLAT PACK



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ORDERING INFORMATION

W S 512K16 - XX X X X

LEAD FINISH:

Blank = Gold plated leads

A = Solder dip leads

DEVICE GRADE:

M = Military Screened -55°C to +125°C

I = Industrial -40°C to +85°C

C = Commercial 0°C to +70°C

PACKAGE TYPE:

DL = 44 Lead Ceramic SOJ (Package 102)

FL = 44 Lead Ceramic Flatpack (Package 209)

ACCESS TIME (ns)

ORGANIZATION, two banks of 256Kx16

SRAM

WHITE ELECTRONIC DESIGNS CORPORATION